

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: C. Chen et al.  
U.S.S.N.: Not Yet Assigned [Divisional of U.S. Serial No. 09/935,312]  
FILED: Herewith  
FOR: CHIP CARRIER, SEMICONDUCTOR PACKAGE AND  
FABRICATING METHOD THEREOF

.....  
**CERTIFICATE OF EXPRESS MAILING**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date July 24, 2003 in an envelope as "Express Mail Post Office to Addressee," mailing Label Number EV343734466US addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By: Michelle P. Chicos  
Michelle P. Chicos

.....  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**PRELIMINARY AMENDMENT**

Applicants kindly request that the above-identified application be amended as follows:

**IN THE SPECIFICATION**

Please **add** the following on page 1 after the title:

**CROSS-REFERENCE TO RELATED APPLICATION(S)**

This application is a divisional of copending application U.S. Serial No. 09/935,312, filed on August 22, 2001.